2SD0592, 2SD0592A (2SD592, 2SD592A)

Silicon NPN epitaxial planer type

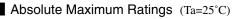
For low-frequency output amplification

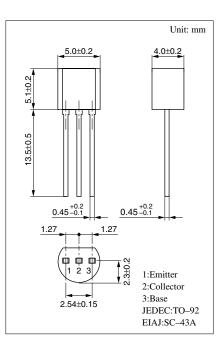
Complementary to 2SB0621 (2SB621) and 2SB0621A (2SB621A)

Features

- Large collector power dissipation P_C .
- Low collector to emitter saturation voltage $V_{CE(sat)}$.

		-				
Parameter		Symbol	Ratings	Unit		
Collector to	2SD0592	V	30	V		
base voltage	2SD0592A	V _{CBO}	60	v		
Collector to	2SD0592	17	25	V		
emitter voltage	2SD0592A	V _{CEO}	50			
Emitter to base voltage		V_{EBO}	5	V		
Peak collector current		I _{CP}	1.5	А		
Collector current		I _C	1	А		
Collector power dissipation		P _C	750	mW		
Junction temperature		Tj	150	°C		
Storage temperature		T _{stg}	-55 ~ +150	°C		





Electrical Characteristics (Ta=25°C)

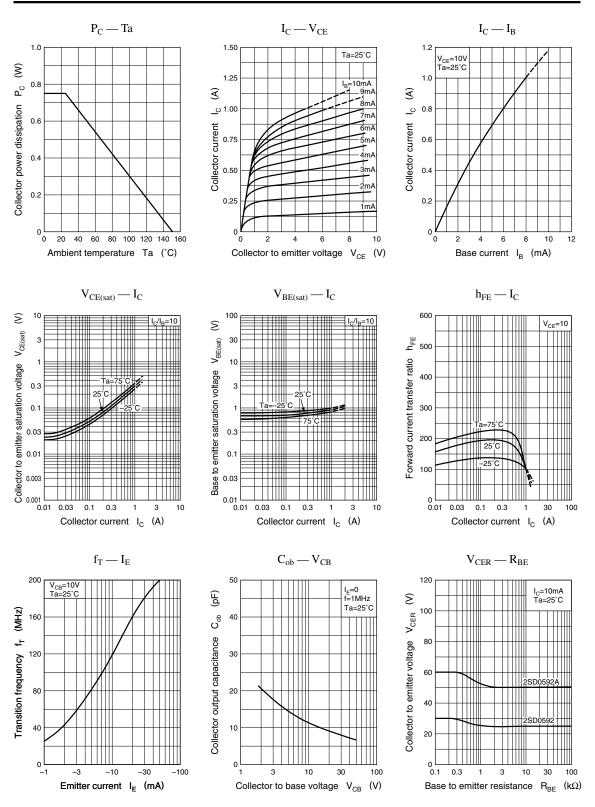
Parameter		Symbol	Conditions	min	typ	max	Unit
Collector cutoff current		I _{CBO}	$V_{CB} = 20V, I_E = 0$			0.1	μΑ
Collector to base	2SD0592	N 7	$I_{\rm C} = 10 \mu A, I_{\rm E} = 0$	30			- v
voltage	2SD0592A	V _{CBO}		60			
Collector to emitter	2SD0592		$I_{\rm C} = 2\mathrm{mA}, I_{\rm B} = 0$	25			v
voltage	2SD0592A	V _{CEO}		50			
Emitter to base voltage		V _{EBO}	$I_{\rm E} = 10 \mu A, I_{\rm C} = 0$	5			v
Forward current transfer ratio		h _{FE1} *1	$V_{CE} = 10V, I_C = 500mA^{*2}$	85	160	340	
		h _{FE2}	$V_{CE} = 5V, I_C = 1A^{*2}$	50			
Collector to emitter saturation voltage V _{CE(sat)}		V _{CE(sat)}	$I_{\rm C} = 500 {\rm mA}, I_{\rm B} = 50 {\rm mA}^{*2}$		0.2	0.4	v
Base to emitter saturation voltage V _{BE(sat}		V _{BE(sat)}	$I_{\rm C} = 500 {\rm mA}, I_{\rm B} = 50 {\rm mA}^{*2}$		0.85	1.2	v
Transition frequency f _T		f _T	$V_{CB} = 10V, I_E = -50mA, f = 200MHz$		200		MHz
Collector output capacitance C _{ob}		C _{ob}	$V_{CB} = 10V, I_E = 0, f = 1MHz$			20	pF

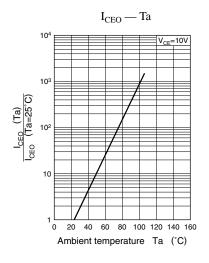
*2 Pulse measurement

*1hFE1 Rank classification

Rank	Q	R	S
h _{FE1}	85 ~ 170	120 ~ 240	170 ~ 340

Note.) The Part numbers in the Parenthesis show conventional part number.





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